

#### TRANSMIT MODULATOR, IF AGC, AND UPCONVERTER

Typical Applications

- CDMA/FM Cellular Systems
- CDMA PCS Systems
- GSM/DCS Systems

- TDMA Systems
- Spread Spectrum Cordless Phones
- Wireless Local Loop Systems

### **Product Description**

The RF2658 is an integrated complete Quadrature Modulator, IF AGC amplifier, and Upconverter developed for the transmit section of dual-mode CDMA/FM cellular and PCS applications and for GSM/DCS and TDMA systems. It is designed to modulate baseband I and Q signals, amplify the resulting IF signals while providing 95dB of gain control range, and perform the final upconversion to UHF. Noise Figure, IP<sub>3</sub>, and other specifications are designed to be compatible with the IS-98 Interim Standard for CDMA cellular communications. This circuit is part of RFMD's line of complete solutions for digital radio applications. The IC is manufactured on an advanced 15GHz  $F_T$  Silicon Bipolar process, and is supplied in a 28-lead plastic SSOP package.







Functional Block Diagram



#### Package Style: QSOP-28

#### Features

- Similar to RF9958 with increased IF range
- Supports Dual Mode Operation
- Digitally Controlled Power Down Modes
- 2.7V to 3.3V Operation
- Double-Balanced UHF Upconvert Mixer
- IF AGC Amp with 95 dB Gain Control

#### Ordering Information RF2658 Transmit Modulator, IF AGC, and Upconverter RF2658 PCBA Fully Assembled Evaluation Board RF Micro Devices, Inc. Tel (336) 664 1233 7628 Thorndike Road Fax (336) 664 0454 Greensboro, NC 27409, USA http://www.fmd.com

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#### **Absolute Maximum Ratings**

Parameter	Rating	Unit
Supply Voltage	-0.5 to +5	V <sub>DC</sub>
Power Down Voltage (V <sub>PD</sub> )	-0.5 to V <sub>CC</sub> +0.7	V
I and Q Levels, per pin	1	V <sub>PP</sub>
LO1 Level, balanced	+3	dBm
LO2 Level, balanced	+6	dBm
Operating Ambient Temperature	-40 to +85	°C
Storage Temperature	-40 to +150	°C



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Parameter	Specification		11.	Condition		
Farameter	Min. Typ.		Max.	Unit	Condition	
					T=25 °C, V <sub>CC</sub> =3.0V, Z <sub>LOAD</sub> =50Ω,	
					LO1 = -8dBm @ 260 MHz,	
I/Q Modulator & AGC					LO2=-3dBm@960MHz,	
					I SIG=Q SIG=300mV <sub>PP</sub> ,	
					RF Output externally matched	
I/Q Input Frequency Range		0 to 20		MHz	Balanced	
I/Q Input Impedance	50	80	110	kΩ	Balanced	
I/Q Input Reference Level		0.6		V <sub>DC</sub>	Per Pin	
LO1/FM Frequency Range		240 to 600		MHz		
LO1/FM Input Level	-15	-8	-5	dBm		
LO1/FM Input Impedance	170	200	230	Ω	Balanced	
Sideband Suppression	35	40		dBc	I/Q Amplitude adjusted to within ±20mV	
		30		dBc	Unadjusted	
Carrier Suppression	40	50		dBc	I/Q DC Offset adjusted to within ±20mV	
		30		dBc	Unadjusted	
Max Output, FM Mode	+2.5	+4		dBm	$V_{GC}=2.5 V_{DC}$	
Max Output, CDMA Mode	-3	0		dBm	$V_{GC}=2.5 V_{DC}$	
Min Output, CDMA Mode		-95	-89	dBm	$V_{GC} = 0.5 V_{DC}$	
Adjacent Channel Power Rejec-		-55		dBc	IS-95A CDMA Modulation	
tion @ 885kHz				ub0	$P_{OUT}$ =-5dBm	
Adjacent Channel Power Rejec-		-67		dBc	IS-95A CDMA Modulation	
tion @ 1.98MHz		01		ub0	$P_{OUT}$ =-5dBm	
Output Noise Power		-116	-111	dBm/Hz	P <sub>OUT</sub> =-3 dBm	
Output Noise Power		-164	-159	dBm/Hz	$P_{OUT} < -70 \text{ dBm}$	
Output Power Accuracy	-3		+3	dB	T=-20 to +85 °C, Ref=25 °C	
Output Impedance	170	200	230	Ω	Balanced	
UHF Upconverter		200	200		Output externally matched	
Conversion Gain	-1	0.5		dB		
Noise Figure (SSB)		15		dB		
Output IP3		+14		dBm		
IF Input Impedance	170	200	230	Ω	Balanced	
IF Input Frequency Range	170	120 to 300	200	MHz		
LO2 Input Impedance		50		Ω	Single Ended	
LO2 Input Level	-6	-3	0	dBm		
LO2 Input Frequency Range	0	700 to 1100	U U	MHz		
RF to LO2 Isolation		20		dB		
Power Supply		20				
Supply Voltage	2.7	3.0	3.3			
Current Consumption	2.1	43	0.0	mA	Modulator and AGC only, CDMA Mode	
Current Consumption		20		mA	Mixer Only	
Power Down Current		20	20	μA		
V <sub>PD</sub> HIGH Voltage	V <sub>CC</sub> -0.7		20	μΛ		
	v.cc-0.7		0.5			
V <sub>PD</sub> LOW Voltage			0.5			

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MODULATORS AND UPCONVERTERS

Pin	Function	Description	Interface Schematic
1	MODE	Selects between CDMA and FM mode. This is a digitally controlled input. A logic "high" ( $\geq V_{CC}$ -0.7 $V_{DC}$ ) selects CDMA mode. A logic "low" ( $\geq 0.5 V_{DC}$ ) selects FM mode. In FM mode, this switch enables the FM amplifier and turns off the I&Q modulator. The impedance on this pin is $30 \text{ k}\Omega$ .	
2	Q SIG	Baseband input to the Q mixer. This pin is DC coupled. The DC level of 0.6 V must be supplied to this pin to bias the transistor. Input impedance of this pin is $50 k\Omega$ minimum.	BIAS BIAS BIAS BIAS BIAS BIAS BIAS C SIG C SIG S
3	Q REF	Reference voltage for the Q mixer. This voltage should be the same as the DC voltage supplied to the Q SIG pin. For maximum carrier suppression, DC voltage on this pin relative to the Q SIG DC voltage may be adjusted. Input impedance of this pin is $50k\Omega$ minimum.	See pin 2.
4	I REF	Reference voltage for the I mixer. This voltage should be the same as the DC voltage supplied to the I SIG pin. For maximum carrier suppression, DC voltage on this pin relative to the I SIG DC voltage may be adjusted. Input impedance of this pin is $50 k\Omega$ minimum.	See pin 5.
5	I SIG	Baseband input to the I mixer. This pin is DC coupled. The DC level of 0.6V must be supplied to this pin to bias the transistor. Input impedance of this pin is $50k\Omega$ minimum.	BIAS 8 kΩ 1 SIG
6	GND1	Ground connection for all baseband circuits including bandgap, AGC, flip-flop, modulator and FM amp. Keep traces physically short and connect immediately to ground plane for best performance.	
7	VCC1	Supply voltage for the LO1 flip-flop and limiting amp only. This supply is isolated to minimize the carrier leakage. A 1 nF external bypass capacitor is required, and an additional 0.1 $\mu$ F will be required if no other low frequency bypass capacitors are nearby. The trace length between the pin and the bypass capacitors should be minimized. The ground side of the bypass capacitors should connect immediately to ground plane. The part is designed to work from 2.7 V to 3.3 V supply.	
8	LO1+, FM+	One half of the balanced modulator LO1 input. The other half of the input, LO1-, is AC grounded for single-ended input applications. The frequency on these pins is divided by a factor of 2, hence the carrier frequency for the modulator becomes one half of the applied frequency. The single-ended input impedance is $100\Omega$ (balanced is $200\Omega$ ). This pin is NOT internally DC blocked. An external blocking capacitor (1 nF recommended) must be provided if the pin is connected to a device with DC present. When FM mode is selected, the output of the flip-flop divider circuit is switched to the AGC amplifier inputs and the modulator mixers are not used. Note that the frequency divider operation.	LO1+, FM+
9	LO1-, FM-	One half of the balanced modulator LO1 input. In single-ended applications (100 $\Omega$ input impedance), this pin is AC grounded with a 1nF capacitor.	See pin 8.
10	BG OUT	Bandgap voltage reference. This voltage, constant over temperature and supply variation, is used to bias internal circuits. A 1nF external bypass capacitor is required.	

Pin	Function	Description	Interface Schematic
11	VCC3	Supply voltage for the AGC and the Bandgap circuitry. A 1 nF external bypass capacitor is required and an additional $0.1\mu$ F will be required if no other low frequency bypass capacitors are nearby. The trace length between the pin and the bypass capacitors should be minimized. The ground side of the bypass capacitors should connect immediately to ground plane. The part is designed to work from 2.7V to 3.3V supply.	
12	GND1	Same as pin 6.	
13	PD1	Power down control for overall circuit. When logic "high" ( $\geq$ V <sub>CC</sub> -0.7V), all circuits are operating; when logic "low" (<0.5V), all circuits are turned off. The input impedance of this pin is >10k $\Omega$ .	PD1 Ο
14	VCC4	Supply for the mixer stage only. The supply for the mixer is separated to maximize IF to RF isolations and reduce the carrier leakage. A 100pF external bypass capacitor is required and an additional $0.1\mu$ F will be required if no other low frequency bypass capacitors are near by. The trace length between the pin and the bypass capacitors should be minimized. The ground side of the bypass capacitors should connect immediately to ground plane. The part is designed to work from 2.7V to 3.3V supply.	
15	PD2	Power down control for mixer only. When connected to pin 10 (BG OUT) the mixer circuits are operating; when connected to ground (≤0.5V), the mixer is turned off but all other circuits are operating.	PD2 0 1 kΩ \$450 Ω
16	GND2	Ground connection for the mixer stage. Keep traces physically short and connect immediately to ground plane for best performance.	
17	RF OUT	RF output pin. An external shunt inductor to $V_{CC}$ plus a series blocking/ matching capacitor are required for 50 $\Omega$ output.	V <sub>2C4</sub> \$300 Ω 
18	DEC	Current mirror decoupling pin. A 1000pF external capacitor is required to bypass this pin. The ground side of the bypass capacitors should connect immediately to ground plane.	
19	LO2+	One half of the balanced mixer LO2 input. In single-ended applications, the other half of the input, LO2- is AC grounded. This is a 50 $\Omega$ impedance port. This pin is NOT internally DC blocked. An external blocking capacitor (100pF recommended) must be provided if the pin is connected to a device with DC present.	$ \begin{array}{c} \begin{array}{c} \begin{array}{c} \begin{array}{c} \begin{array}{c} \begin{array}{c} \end{array} \\ \end{array} \\ \end{array} \\ \end{array} \\ \begin{array}{c} \end{array} \\ 40 \Omega \\ \end{array} \\ \begin{array}{c} \end{array} \\ \end{array} \\ \end{array} \\ \end{array} \\ \begin{array}{c} \end{array} \\ \end{array} \\$
20	LO2-	One half of the balance mixer LO2 input. In single ended applications, this pin is AC grounded with a 100pF capacitor.	See pin 19.
21	MIX IN-	One half of the $200\Omega$ balanced impedance input to the mixer stage. This pin is NOT internally DC blocked. An external blocking capacitor (2200pF recommended) must be provided if the pin is connected to a device with DC present. If no IF filter is needed, this pin may be con- nected to MOD OUT+ through a DC blocking capacitor. An appropriate matching network may be needed if an IF filter is used.	BIAS BIAS ξ100 Ω ξ100 Ω MIX IN- MIX IN

Same as pin 21, except complementary input.

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See pin 21.

— LO2-

- MIX IN+

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MIX IN+

Pin	Function	Description	Interface Schematic
23	GND2	Same as pin 16.	
24	MOD OUT-	One half of the balanced AGC output port. The impedance of this port is $200\Omega$ balanced. If no filtering is required, this pin can be connected to the MIX IN- pin through a DC blocking capacitor. This pin requires an inductor to V <sub>CC</sub> to achieve full dynamic range. In order to maximize gain, this inductor should be a high-Q type and should be parallel resonated out with a capacitor (see application schematic). This pin is NOT DC blocked. A blocking capacitor of 2200pF is needed when this pin is connected to a DC path. An appropriate matching network may be needed if an IF filter is used.	V <sub>CC3</sub> V <sub>CC3</sub>
25	MOD OUT+	Same as pin 24, except complementary output.	See pin 24.
26	DEC	AGC decoupling pin. An external bypass capacitor of 10nF capacitor is required. The trace length between the pin and the bypass capacitors should be minimized. The ground side of the bypass capacitors should connect immediately to ground plane.	
27	GC	Analog gain control for AGC amplifiers. Valid control voltage ranges are from $0.5V_{DC}$ to $2.5V_{DC}$ . The gain range for the AGC is 88dB. These voltages are valid ONLY for a $37k\Omega$ source impedance.	GC 0 = BIAS 21 kΩ 40 kΩ =
28	VCC2	Supply for the modulator stage only. A 10nF external bypass capacitor is required and an additional $0.1\mu$ F will be required if no other low frequency bypass capacitors are nearby. The trace length between the pin and the bypass capacitors should be minimized. The ground side of the bypass capacitors should connect immediately to ground plane. The part is designed to work from 2.7 V to 3.3 V supply.	

## RF2658 Pin-Out

MODE 1	28 VCC2
Q SIG 2	27 GC
Q REF 3	26 DEC
I REF 4	25 MOD OUT+
I SIG 5	24 MOD OUT-
GND1 6	23 GND2
VCC1 7	22 MIX IN+
LO1+ 8	21 MIX IN-
LO1-9	20 LO2-
BG OUT 10	19 LO2+
VCC311	18 DEC
GND1 12	17 RF OUT
PD1 13	16 GND2
VCC414	15 PD2

MODULATORS AND UPCONVERTERS

## **Application Schematic**



**Evaluation Board Schematic** (Download Bill of Materials from www.rfmd.com.) P3 P1 P2 P1-1 () 1 <MODE P2-1 ()-<vcc 1 <GND 1 파 ⊪ 2 <GND ⊪ 2 <GND 2 P1-3 ()-3 <GC P2-3 ()-3 <I REF 3 P3-4 ()--<PD1 4 ⊪ <GND 5 MODE O-C9 ⊤ 10 nF MODE VCC2 28 R2 R1 1 .13  $10 \, k\Omega$  $27 \, k\Omega$ Q SIG  $\sim$  $\sim$ Q SIG GC 2 27 C8 C10 10 nF 1 nF I REF O 3 Q REF DEC 26 ++40 50 Ω µstrip C2 T1 C19 Ť \_\_10 nF 1 μF 4 I REF MOD OUT+ 25 23 J2 I SIG MOD OUT-5 24 I SIG 🤤 \_ C15 C16 10 nF 1 6 GND1 GND2 23 2.2 nF 50 Ω µstrip

7 VCC1

8 LO1+

9 LO1-

11 VCC3

12 GND1

13 PD1

14 VCC4

C6

⊤1 nF

10 BG OUT

C1

1 nF

C3

1 nF

4 |-

C4

100 nF

C5

-1 nF

\_ C20

1 μF

50  $\Omega$  µstrip

.11

PD1 ()

vcc O-

C17

2.2 nF

+

\_\_\_\_ C12

100 pF

\_||-C11

1000 pF

MIX IN+

MIX IN-

LO2- 20

LO2+ 19

DEC 18

**RF OUT** 

GND2

PD2 15

R3

0Ω

 $\sim$ 

22

21

17

16

13 ||

40

Jı.

2

T2 -

-||-C18

100 pF

C13

33 pF

-++

L2 12 nH

C7

1 nH

L1

15 nH

 $\sim$ 

C14

1.3 pF

-O VCC

Т

Ŧ

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**RF2658** 

Rev A8 010720

-O VCC

-O VGC

O VCC

J7

RF OUT

(0)

 $50~\Omega~\mu strip$ 

 $50 \ \Omega \ \mu strip$ 

J5

J4 MOD OUT



Evaluation Board Layout Board Size 2.689" x 2.521"

